REPLY UNDER 37 C.F.R. §1.116 EXPEDITED PROCEDURE TECHNOLOGY CENTER 2643

APPL. SERIAL NO. 09/910,110 ATTY DOCKET: 30521/071

STATUS OF THE CLAIMS

What is claimed is:

- (Currently Amended) A raised microstructure for use in a silicon based device,
 the raised microstructure comprising:
 - a generally planar thin-film plate having a periphery;
 - a <u>ribbed</u> sidewall <u>including a plurality of ridges and grooves, the ribbed</u>

 <u>sidewall arranged to support the generally planar thin-film plate along</u>

 <u>the periphery; supporting the film;</u>
 - wherein the <u>plurality of ridges and grooves of the ribbed</u> sidewall <u>form has</u> at least one rib <u>formed therein</u>, and wherein the at least one rib <u>stiffens</u> the ribbed sidewall.
- (Currently Amended) The raised microstructure of claim 1 wherein the <u>ridges</u>
 and grooves of the <u>ribbed</u> sidewall <u>are parallel</u> and equally spaced to form a
 corrugated sidewall is <u>corrugated</u>.
- 3. (Original) The raised microstructure of claim 1 wherein the rib has a generally arcuate cross section.
- (Previously Presented) The raised microstructure of claim 1 wherein the rib has a generally triangular cross section.
- 5. (Original) The raised microstructure of claim 1 wherein the rib has a generally rectangular cross section.

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- 6. (Original) The raised microstructure of claim 1 wherein the thin-film comprises one plate of a silicon based capacitive transducer.
- 7. (Original) The raised microstructure of claim 1 wherein the thin-film comprises a rigid backplate of a silicon based microphone.
- 8. (Currently Amended) A silicon based electret microphone having a backplate comprising:
 - a generally planar thin-film plate;
 - a sidewall having a plurality of ridges and grooves, the sidewall arranged to support the thin-film plate supporting the film;
 - wherein the plurality of ridges and grooves of the sidewall cooperate to form has at least one rib formed therein.
- 9. (Currently Amended) The microphone of claim 8 wherein the <u>ridges and</u>
 grooves of the ribbed sidewall <u>are parallel and equally spaced to form a</u>
 corrugated sidewall is corrugated.
- 10. (Original) The microphone of claim 8 wherein the rib has a generally arcuate cross section.
- 11. (Previously Presented) The microphone of claim 8 wherein the rib has a generally triangular cross section.

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- 12. (Previously Presented) The microphone of claim 8 wherein the rib has a generally rectangular cross section.
- 13. (Original) The microphone of claim 8 wherein the sidewall includes a plurality of ribs.
- 14. (Original) The microphone of claim 13, wherein the ribs are equally spaced about the sidewall.
- 15. (Currently Amended) A raised microstructure for use in a silicon based device, the raised microstructure comprising:

generally planar element with a first thickness and a periphery;

- a sidewall <u>including a plurality of ridges and grooves, the sidewall having with</u>
 a second thickness;
- said sidewall supporting said planar element at said periphery above a substrate at a distance;
- wherein said <u>plurality of ridges and grooves of the</u> sidewall <u>cooperate to form</u>

 has a plurality of ribs formed therein.
- 16. (Original) The raised microstructure of claim 15 wherein said first thickness is small compared to the lateral extent of the said planar element.
- 17. (Original) The raised microstructure of claim 15 wherein said second thickness is approximately equal to the said first thickness.

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- 18. (Original) The raised microstructure of claim 15 wherein said distance is large compared to said second thickness.
- 19. (Original) The raised microstructure of claim 15 wherein the ribs follow a periodic path of the periphery, inwards and outwards with respect to the centroid of the planar element.
- 20. (Original) The raised microstructure of claim 19 wherein the path is arcuate.
- 21. (Previously Presented) The raised microstructure of claim 1 wherein the sidewall substantially completely encloses the area beneath the thin-film.
- 22. (Previously Presented) The microphone of claim 8 wherein the sidewall substantially completely encloses the area beneath the thin-film.
- 23. (Previously Presented) The raised microstructure of claim 15 wherein the sidewall substantially completely encloses the area beneath the element.